

## 1. General description

AC Thyristor Triac power switch in a TO263 (D2PAK) surface mountable plastic package with self-protective clamping capabilities against low and high energy transients. This "series CTN" triac will commute the full RMS current at the maximum rated junction temperature ( $T_{j(max)} = 150\text{ °C}$ ) without the aid of a snubber. It is used in applications where "high junction operating temperature capability" is required.

## 2. Features and benefits

- Clamping structure ensuring safe high over-voltage withstand capability
- High junction operating temperature capability ( $T_{j(max)} = 150\text{ °C}$ )
- High minimum IGT for guaranteed immunity to gate noise
- Full cycle AC conduction
- Over-voltage withstand capability to IEC 61000-4-5
- Pin compatible with standard triacs
- Planar passivated for voltage ruggedness and reliability
- Protective self turn-on capability for high energy transients
- Safe clamping capability for low energy over-voltage transients
- Less sensitive gate for high noise immunity
- Surface mountable package
- Triggering in three quadrants only
- Very high immunity to false turn-on by  $dV/dt$  and IEC 61000-4-4 fast transient
- Package meets UL94V0 flammability requirement
- Package is RoHS compliant

## 3. Applications

- AC fan, pump and compressor controls
- Highly inductive, resistive and safety loads
- Large and small appliances (White Goods)
- Reversing induction motor controls
- Applications subject to high temperature ( $T_{j(max)} = 150\text{ °C}$ )

## 4. Quick reference data

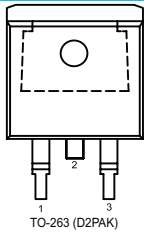
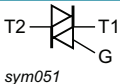
Table 1. Quick reference data

Symbol	Parameter	Conditions	Values	Unit
<b>Absolute maximum rating</b>				
$V_{DRM}$	repetitive peak off-state voltage		800	V
$I_{T(RMS)}$	RMS on-state current	square-wave pulse; $T_{mb} \leq 126\text{ °C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>	10	A
$I_{TSM}$	non-repetitive peak forward current	full sine wave; $t_p = 20\text{ ms}$ ; $T_{j(init)} = 25\text{ °C}$ ; <a href="#">Fig. 4</a> ; <a href="#">Fig. 5</a>	90	A
		full sine wave; $t_p = 16.7\text{ ms}$ ; $T_{j(init)} = 25\text{ °C}$	99	A
$T_j$	junction temperature		150	°C

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$I_{GT}$	gate trigger current	$V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2+ G+ $T_j = 25\text{ }^\circ\text{C}$ ; Fig. 7	5	-	35	mA
		$V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2+ G- $T_j = 25\text{ }^\circ\text{C}$ ; Fig. 7	5	-	35	mA
		$V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2- G- $T_j = 25\text{ }^\circ\text{C}$ ; Fig. 7	5	-	35	mA
$I_H$	holding current	$V_D = 12\text{ V}$ ; $T_j = 25\text{ }^\circ\text{C}$ ; Fig. 9	-	-	30	mA
$V_T$	on-state voltage	$I_T = 14\text{ A}$ ; $T_j = 25\text{ }^\circ\text{C}$ ; Fig. 10	-	-	1.5	V
<b>Dynamic characteristics</b>						
$dV_D/dt$	rate of rise of off-state voltage	$V_{DM} = 536\text{ V}$ ; $T_j = 125\text{ }^\circ\text{C}$ ; ( $V_{DM} = 67\%$ of $V_{DRM}$ ); exponential waveform; gate open circuit	4000	-	-	V/ $\mu\text{s}$
		$V_{DM} = 536\text{ V}$ ; $T_j = 150\text{ }^\circ\text{C}$ ; ( $V_{DM} = 67\%$ of $V_{DRM}$ ); exponential waveform; gate open circuit	2000	-	-	V/ $\mu\text{s}$
$dI_{com}/dt$	rate of change of commutating current	$V_D = 400\text{ V}$ ; $T_j = 150\text{ }^\circ\text{C}$ ; $I_{T(RMS)} = 10\text{ A}$ ; $dV_{com}/dt = 20\text{ V}/\mu\text{s}$ ; gate open circuit; snubberless condition	5	-	-	A/ms
		$V_D = 400\text{ V}$ ; $T_j = 150\text{ }^\circ\text{C}$ ; $I_{T(RMS)} = 10\text{ A}$ ; $dV_{com}/dt = 10\text{ V}/\mu\text{s}$ ; gate open circuit	10	-	-	A/ms
		$V_D = 400\text{ V}$ ; $T_j = 150\text{ }^\circ\text{C}$ ; $I_{T(RMS)} = 10\text{ A}$ ; $dV_{com}/dt = 1\text{ V}/\mu\text{s}$ ; gate open circuit	15	-	-	A/ms

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T1	main terminal 1		
2	T2	main terminal 2		
3	G	gate		
mb	T2	mounting base; main terminal 2		

## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
ACTT10B-800CTN	D2PAK	plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped)	TO-263

## 7. Marking

Table 4. Marking codes

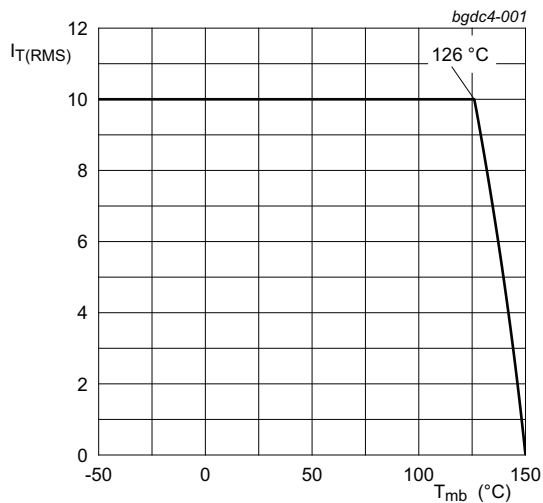
Type number	Marking codes
ACTT10B-800CTN	ACTT10B-800CTN

## 8. Limiting values

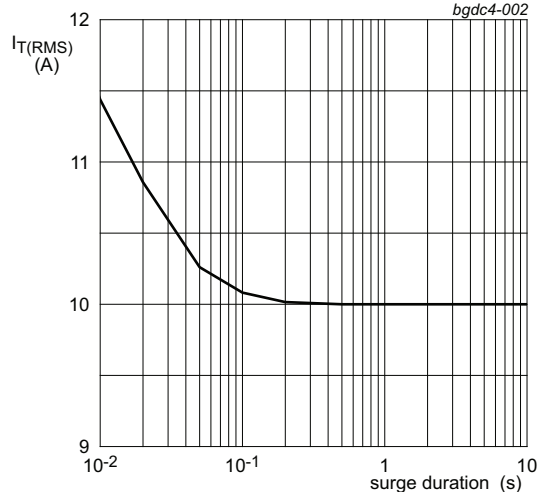
**Table 4. Limiting values**

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Values	Unit
$V_{\text{DRM}}$	repetitive peak off-state voltage		800	V
$I_{\text{T(RMS)}}$	RMS on-state current	full sine wave; $T_{\text{mb}} \leq 126^\circ\text{C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>	10	A
$I_{\text{TSM}}$	non-repetitive peak on-state current	full sine wave; $t_p = 20 \text{ ms}$ ; $T_{\text{j(init)}} = 25^\circ\text{C}$ ; <a href="#">Fig. 4</a> ; <a href="#">Fig. 5</a>	90	A
		full sine wave; $t_p = 16.7 \text{ ms}$ ; $T_{\text{j(init)}} = 25^\circ\text{C}$	99	A
$I^2t$	$I^2t$ for fusing	$t_p = 10 \text{ ms}$ ; sine wave	40	$\text{A}^2/\text{s}$
$dI_{\text{T}}/dt$	rate of rise of on-state current	$I_{\text{G}} = 70 \text{ mA}$	100	$\text{A}/\mu\text{s}$
$I_{\text{GM}}$	peak gate current		2	A
$P_{\text{GM}}$	peak gate power		5	W
$P_{\text{G(AV)}}$	average gate power	over any 20 ms period	0.5	W
$T_{\text{stg}}$	storage temperature		-40 to 150	$^\circ\text{C}$
$T_{\text{j}}$	junction temperature		150	$^\circ\text{C}$
$V_{\text{pp}}$	peak pulse voltage	$T_{\text{j}} = 25^\circ\text{C}$ ; non-repetitive, off-state; ten pulses on each voltage polarity; 20s or more between successive pulses	2	kV



**Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values**



$f = 50 \text{ Hz}$ ;  $T_{\text{mb}} = 126^\circ\text{C}$

**Fig. 2. RMS on-state current as a function of surge duration; maximum values**

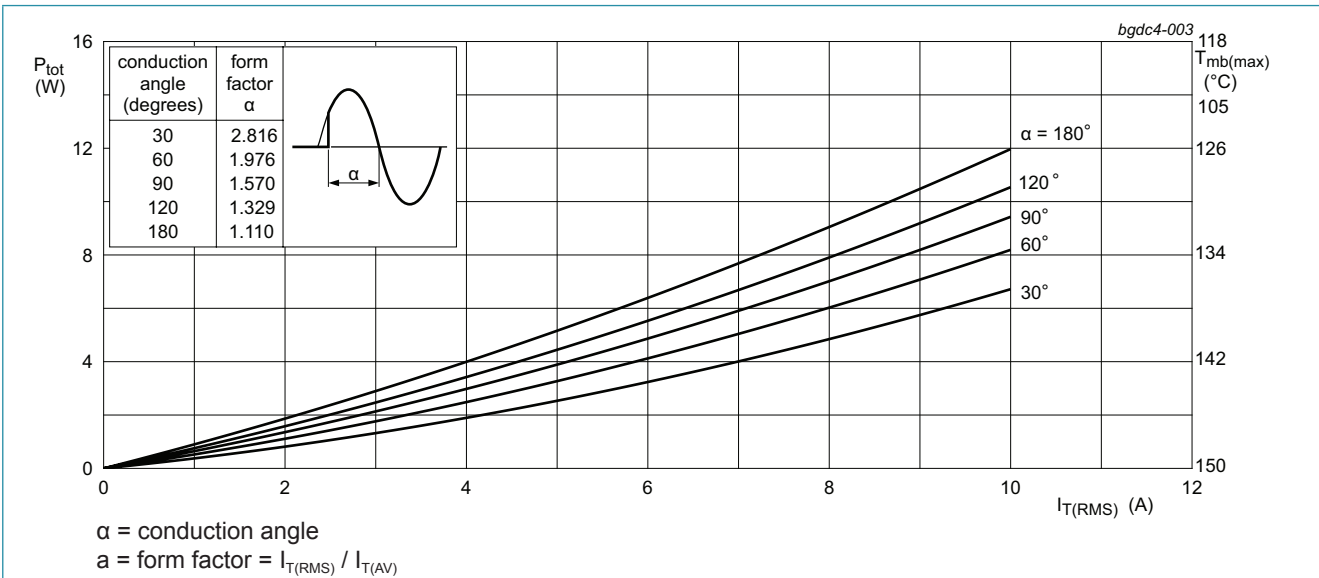


Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

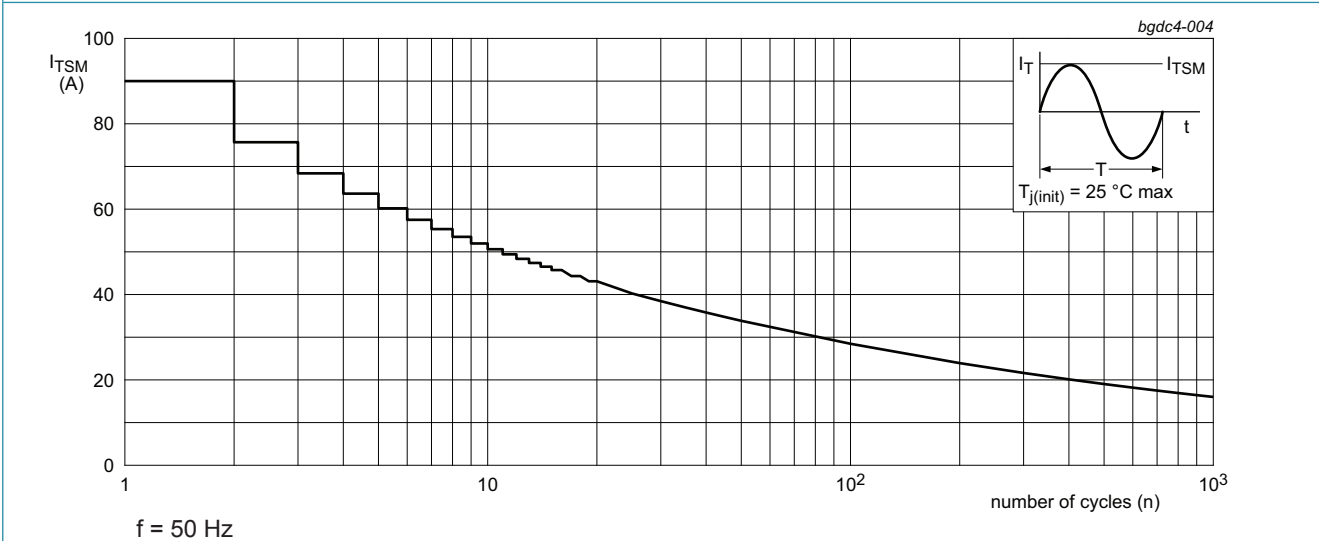


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

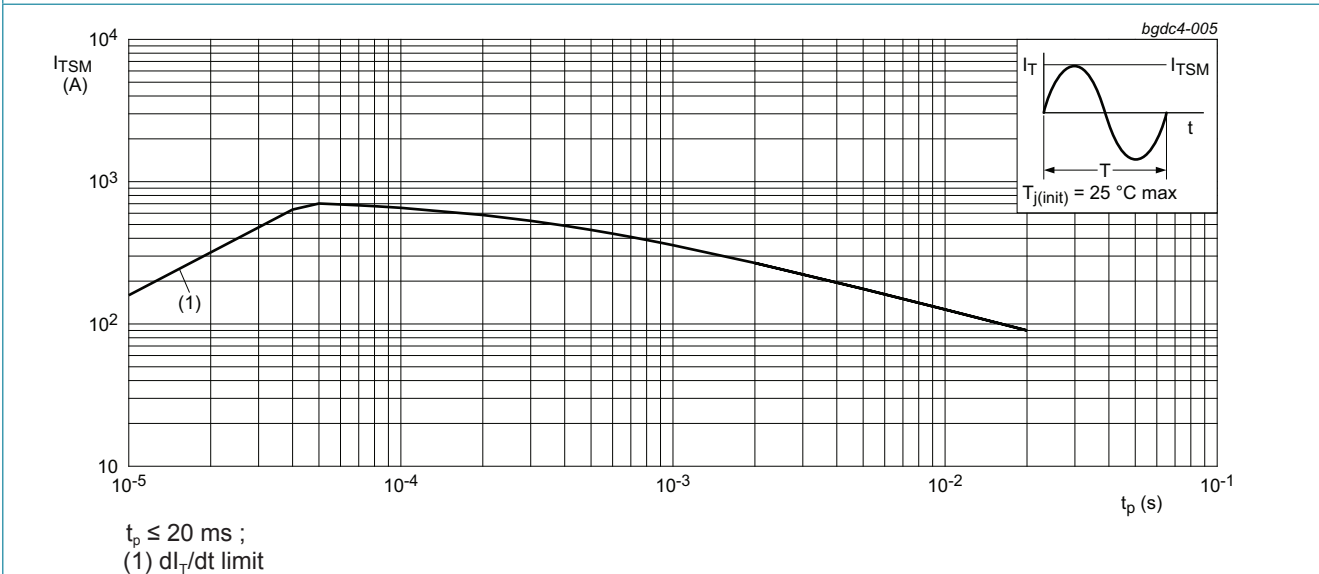
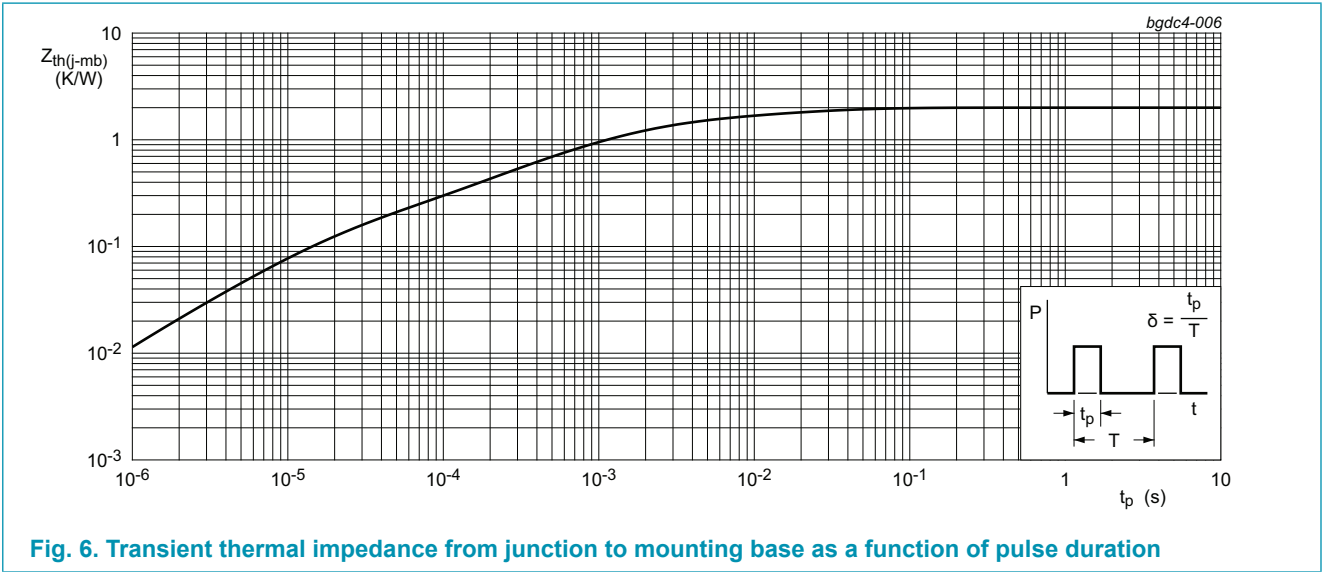


Fig. 5. Total power dissipation as a function of RMS on-state current; maximum values

9. Thermal characteristics

Table 5. Thermal characteristics

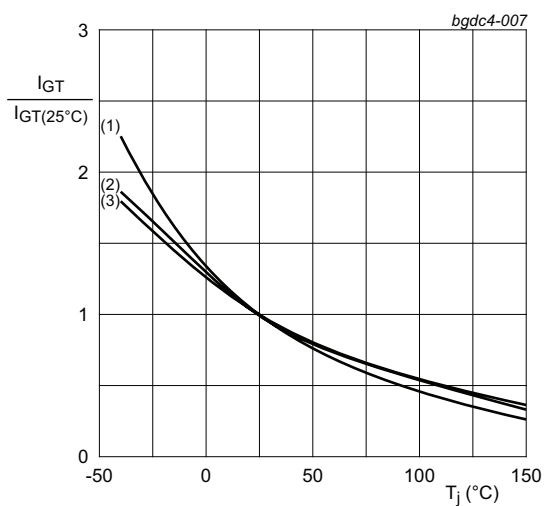
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	<a href="#">Fig. 6</a>		-	-	2	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air		-	55	-	K/W



## 10. Characteristics

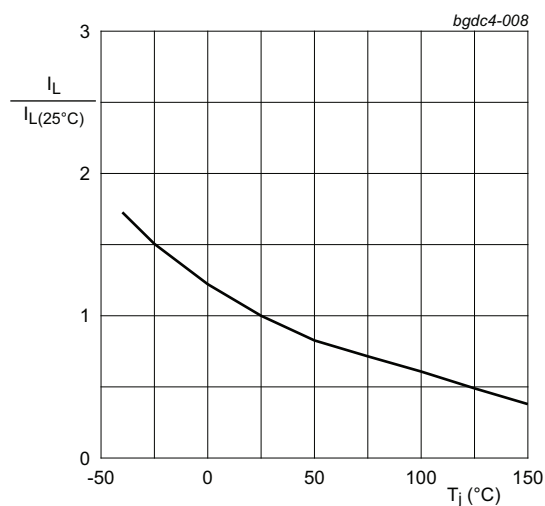
Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
I <sub>GT</sub>	gate trigger current	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2+ G+; T <sub>J</sub> = 25 °C; <a href="#">Fig. 7</a>		5	-	35	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2+ G-; T <sub>J</sub> = 25 °C; <a href="#">Fig. 7</a>		5	-	35	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2- G-; T <sub>J</sub> = 25 °C; <a href="#">Fig. 7</a>		5	-	35	mA
I <sub>L</sub>	latching current	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2+ G+; T <sub>J</sub> = 25 °C; <a href="#">Fig. 8</a>		-	-	40	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2+ G-; T <sub>J</sub> = 25 °C; <a href="#">Fig. 8</a>		-	-	50	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2- G-; T <sub>J</sub> = 25 °C; <a href="#">Fig. 8</a>		-	-	40	mA
I <sub>H</sub>	holding current	V <sub>D</sub> = 12 V; T <sub>J</sub> = 25 °C; <a href="#">Fig. 9</a>		-	-	30	mA
V <sub>T</sub>	on-state voltage	I <sub>T</sub> = 14 A; T <sub>J</sub> = 25 °C; <a href="#">Fig. 10</a>		-	-	1.5	V
V <sub>GT</sub>	gate trigger voltage	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T <sub>J</sub> = 25 °C; <a href="#">Fig. 11</a>		-	0.8	1	V
		V <sub>D</sub> = 400 V; I <sub>T</sub> = 0.1 A; T <sub>J</sub> = 150 °C; <a href="#">Fig. 11</a>		0.2	0.45	-	V
I <sub>D</sub>	off-state current	V <sub>D</sub> = 800 V; T <sub>J</sub> = 25 °C		-	-	10	μA
		V <sub>D</sub> = 800 V; T <sub>J</sub> = 150 °C		-	-	2	mA
Dynamic characteristics							
dV <sub>D</sub> /dt	rate of rise of off-state voltage	V <sub>DM</sub> = 536 V; T <sub>J</sub> = 125 °C; (V <sub>DM</sub> = 67% of V <sub>DRM</sub> ); exponential waveform; gate open circuit		4000	-	-	V/μs
		V <sub>DM</sub> = 536 V; T <sub>J</sub> = 150 °C; (V <sub>DM</sub> = 67% of V <sub>DRM</sub> ); exponential waveform; gate open circuit		2000	-	-	V/μs
dI <sub>com</sub> /dt	rate of change of commutating current	V <sub>D</sub> = 400 V; T <sub>J</sub> = 150 °C; I <sub>T(RMS)</sub> = 10 A; dV <sub>com</sub> /dt = 20 V/μs; gate open circuit; snubberless condition		5	-	-	A/ms
		V <sub>D</sub> = 400 V; T <sub>J</sub> = 150 °C; I <sub>T(RMS)</sub> = 10 A; dV <sub>com</sub> /dt = 10 V/μs; gate open circuit		10	-	-	A/ms
		V <sub>D</sub> = 400 V; T <sub>J</sub> = 150 °C; I <sub>T(RMS)</sub> = 10 A; dV <sub>com</sub> /dt = 10 V/μs; gate open circuit		15	-	-	A/ms

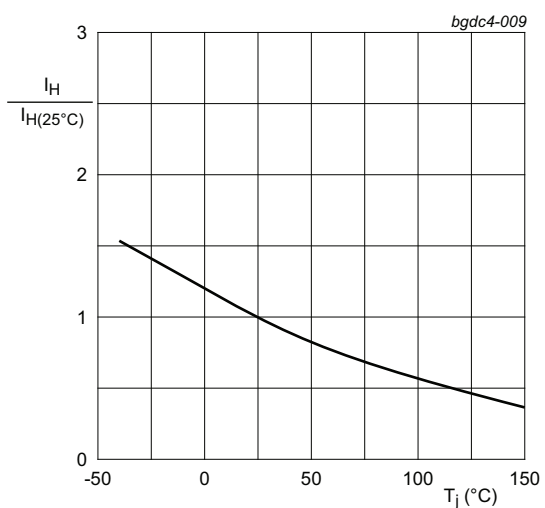


- (1) T2- G-  
(2) T2+ G-  
(3) T2+ G+

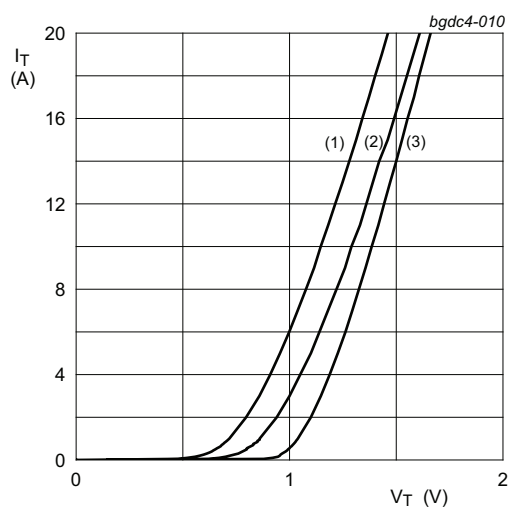
**Fig. 7. Normalized gate trigger current as a function of junction temperature**



**Fig. 8. Normalized latching current as a function of junction temperature**



**Fig. 9. Normalized holding current as a function of junction temperature**



$V_o = 0.962 \text{ V}$ ;  $R_s = 0.0330 \text{ } \Omega$

- (1)  $T_j = 150 \text{ } ^\circ\text{C}$ ; typical values  
(2)  $T_j = 150 \text{ } ^\circ\text{C}$ ; maximum values  
(3)  $T_j = 25 \text{ } ^\circ\text{C}$ ; maximum values

**Fig. 10. On-state current as a function of on-state voltage**

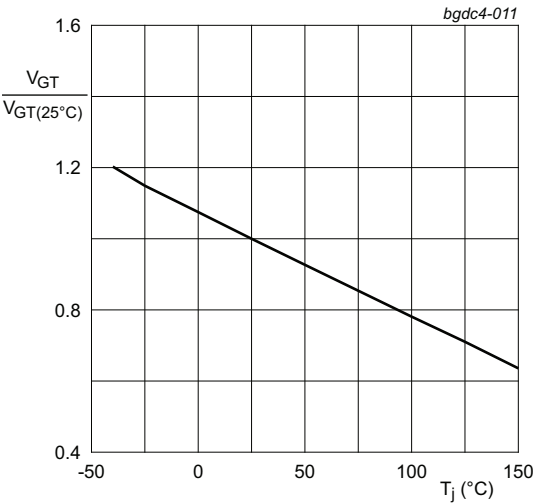
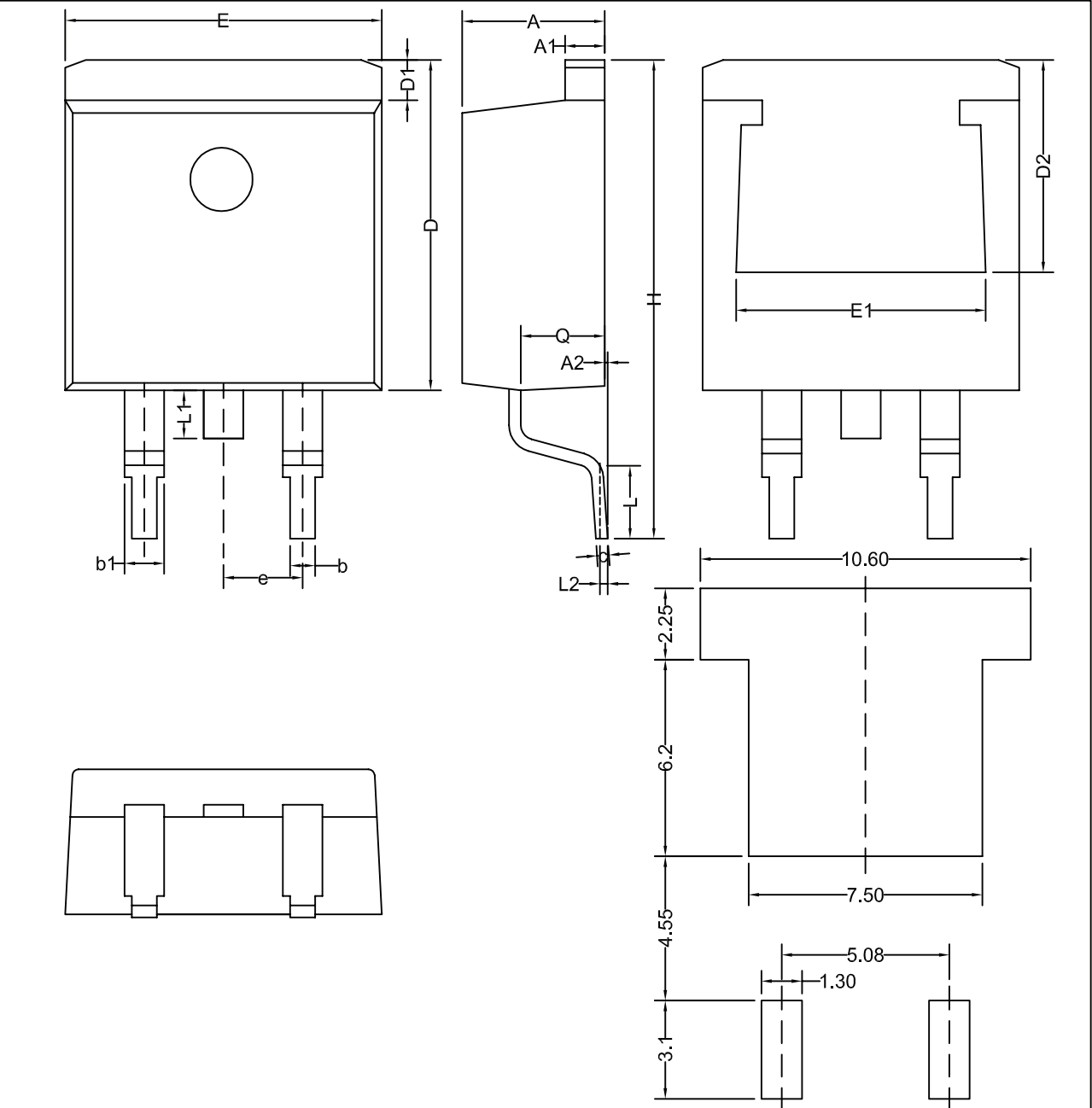


Fig. 11. Normalized gate trigger voltage as a function of junction temperature



11. Package outline

Plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped) TO263



Recommended Footprint

Unit	A	A1	A2	b	b1	c	D	D1	D2	e	E	E1	H	L	L1	L2	Q
min	4.10	1.22	0.00	0.60	1.05	0.34	---	1.20	6.60	2.54 (BSC)	9.70	7.80	14.80	2.10	---	0.25 (BSC)	2.20
max	4.70	1.40	0.25	0.90	1.45	0.64	11.00	1.60	---	---	10.30	---	15.80	2.90	1.75	---	2.79

## 12. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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